ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES® international and Par	PC. Bannockl	ourn, Illinois, A	Il rights reserved untions.	under both	This docume level parts, t	ent is a declaration entities the declaration entities and the declaration entities and the declaration entities and the declaration entities are an entities and the declaration entities are an entities and the declaration entities are an entite are an entities are an entities are an entite are	on of the su	bstances v all lower	vithin the manufactu level materials for v	rer listed	item. Note: nanufactur	if the item is an as er has engineering	sembly with low responsibility.	
	IPC Web Site for Information on IPC-1752 StandardForm Distrhttp://www.ipc.org/IPC-175xForm				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Informa					ation				
upplier Information														
Company name* Company			any unique ID			Unique ID Authority				Respon	Response Date*			
nsemi											2024-06-06			
ntact Name Title - Contact			ct			Phone - Contact*				Email -	Email - Contact*			
Product-Env-Stewards Product Envir			nviro Compliance			NA				Product-Env-Stewards@onsemi.com				
Authorized Representative* Title - Represe			sentative			Phone - Representative*			Email -	Email - Representative*				
Product-Env-Stewards Product Er			ct Enviro Compliance			NA				Produ	Product-Env-Stewards@onsemi.com			
Requester Item Number	Mfr Item	Number	Mfr Item Name			Effective Date	Version	М	Manufacturing Site		Weight*	UOM	Unit Type	
	1PMT59	PMT5929BT1G ZEN PWMITE		E REG 3.2W 6.2V		2024-06-06		М	MY1		16.3	mg	Each	
Ianufacturing Proccess Information	tion							ŕ						
Terminal Plating / Grid Array Ma	terial T	rial Terminal Base Allo		J-STD-020 MSL Rating		Peak Proce	Peak Process Body Temperate		ure Max Time at Peak Temp		ture Nun	nber of Reflow Cyc	les	
Matte Tin (Sn) - annealed CU Alloy		CU Alloy		1		260		С	30	seco	nds 3			
omments														
vel 1 - maximum time at peak temperatu	re during so	Idering is 10-3	0 seconds											
or more information regarding material	composition	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	(Pb), Mercury (Hg), Hexavalent Chro	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Dibutyl phthalate (DIBP).										
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier may have relied on informationprovided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, itssuppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of the agreement, will be the sole and exclusivesource of the Supplier's Itality and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms andConditions of Sale applicable to such part shall apply.												
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted							
Exemption: 7a: Lead in high melting temp	erature type solders (i.e. lead based sol	der alloys containing 85% by weight or m	ore lead).									
Exemption List Version	EL-2011/534/EU											
Declaration Signature												
Instructions: Complete all of the required Requester) and click on Submit Form to h			e drop-dowi	a. This will display the signature area. Digita	lly sign the declaration (if required by the							
Supplier Digital Signature	astislav Drska	Le										

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.16	mg	Supplier	Silicon (Si)	7440-21-3		0.16	mg
Die Attach Solder	0.34	mg	Supplier	Silver (Ag)	7440-22-4		0.0085	mg
			А	Lead (Pb)	7439-92-1	7a	0.3145	mg
			Supplier	Tin (Sn)	7440-31-5		0.017	mg
Lead Frame	5.38	mg	Supplier	Zinc (Zn)	7440-66-6		0.0054	mg
			Supplier	Iron (Fe)	7439-89-6		0.1291	mg
			Supplier	Copper (Cu)	7440-50-8		5.2455	mg
Mold Compound-Black	9.69	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		0.969	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0484	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		1.405	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		6.2985	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.969	mg
Plating	0.73	mg	Supplier	Tin (Sn)	7440-31-5		0.73	mg